L Number	Hits	Search Text	DB	Time stamp
1	1958322		USPAT;	2004/03/30 08:09
1			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1			IBM TDB	
2	332811	stainless adj steel	USPAT;	2004/03/30 08:09
		-	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	2125	ivar	USPAT;	2004/03/30 08:09
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
			IBM TDB	
4	8649	polishing with (table support)	USPAT;	2004/03/30 08:09
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
5	88	(wafer wafers substrate substrates) same	USPAT;	2004/03/30 08:22
		(polishing with (table support)) same	US-PGPUB;	
		((stainless adj steel) ivar)	EPO; JPO;	
			DERWENT;	
			IBM_TDB]
6	3616	work adj holder	USPAT;	2004/03/30 08:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
7	1044944	carrier	USPAT;	2004/03/30 08:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
8	2723491	plate	USPAT;	2004/03/30 08:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	
9	3560663	(work adj holder) carrier plate	USPAT;	2004/03/30 08:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		l	IBM_TDB	
10	72000	silicon adj carbide	USPAT;	2004/03/30 08:22
]			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1,,	66000	us; cu	IBM_TDB	0004/00/00 00 00
11	66222	"SiC"	USPAT;	2004/03/30 08:22
			US-PGPUB;	
]			EPO; JPO;	
			DERWENT;	
12	118961	(silicon adj carbide) "SiC"	IBM_TDB	2004/02/20 00:00
**	110201	(SIIICON AU) CAIDIUE) "SIC"	USPAT; US-PGPUB;	2004/03/30 08:22
			EPO; JPO; DERWENT;	
			IBM TDB	
13	6535	((work adj holder) carrier plate) with	USPAT;	2004/03/30 08:30
	0555	((silicon adj carbide) "SiC")	US-PGPUB;	2004/03/30 08:30
		((STITEON GG) CALDIGE; SIC	EPO; JPO;	
			DERWENT;	
			IBM TDB	
14	1201	(((work adj holder) carrier plate) with	USPAT;	2004/03/30 00:00
* 7	1201	((work ad) horder) carrier plate) with ((silicon adj carbide) "SiC")) with (wafer	USPAT; US-PGPUB;	2004/03/30 08:23
		((Silicon adj Carbide) "SiC")) with (Waler wafers substrate substrates)	EPO; JPO;	
		waters substrate substrates)	DERWENT;	1
			IBM TDB	
L			TOM INR	

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15	F01020	ribe recesses	USPAT;	2004/03/30 08:23
1 1 2	301920	ribs recesses	US-PGPUB;	2004/03/30 08:23
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
16	7	((((work adj holder) carrier plate) with	USPAT;	2004/03/30 08:25
10	1	((silicon adj carbide) "SiC")) with (wafer	US-PGPUB;	2004/03/30 00:23
		wafers substrate substrates)) with (ribs	EPO; JPO;	
		recesses)	DERWENT;	
		10003007	IBM TDB	
17	8	((((work adj holder) carrier plate) with	USPAT;	2004/03/30 08:24
-		((silicon adj carbide) "SiC")) with (wafer	US-PGPUB;	2001,03,30 00.21
		wafers substrate substrates)) same (ribs	EPO; JPO;	
		recesses)	DERWENT;	
		10000000	IBM TDB	
18	1	(((((work adj holder) carrier plate) with	USPAT;	2004/03/30 08:24
- "	_	((silicon adj carbide) "SiC")) with (wafer	US-PGPUB;	2001,00,00 00.21
		wafers substrate substrates)) same (ribs	EPO; JPO;	
		recesses)) not ((((work adj holder)	DERWENT;	
		carrier plate) with ((silicon adj carbide)	IBM TDB	
		"SiC")) with (wafer wafers substrate		
		substrates)) with (ribs recesses))		
19	8		USPAT;	2004/03/30 08:26
		((silicon adj carbide) "SiC")) with (wafer	US-PGPUB;	
		wafers substrate substrates)) same (ribs	EPO; JPO;	
		recesses)	DERWENT;	
			IBM TDB	
20	60	((((work adj holder) carrier plate) with	USPAT;	2004/03/30 08:26
		((silicon adj carbide) "SiC")) with (wafer	US-PGPUB;	
		wafers substrate substrates)) and (ribs	EPO; JPO;	
		recesses)	DERWENT;	
İ			IBM_TDB	
21	52		USPAT;	2004/03/30 08:26
		((silicon adj carbide) "SiC")) with (wafer	US-PGPUB;	
		wafers substrate substrates)) and (ribs	EPO; JPO;	
İ		recesses)) not ((((work adj holder)	DERWENT;	
		carrier plate) with ((silicon adj carbide)	IBM_TDB	
		"SiC")) with (wafer wafers substrate		
22	,	substrates)) same (ribs recesses))	HODAM.	2004/03/30 08:34
22	1	(USPAT;	2004/03/30 08:34
		((silicon adj carbide) "SiC") same (ribs recesses) same ((rear back) adj (surface	US-PGPUB; EPO; JPO;	
		recesses) same ((rear back) adj (surface face))	DERWENT;	
		Lace,	IBM TDB	
23	1254	451/398	USPAT;	2004/03/30 08:34
	1253	101/000	US-PGPUB;	2001,03,30 00.31
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
24	947	451/398.ccls.	USPAT;	2004/03/30 08:34
	1		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
25	14	((silicon adj carbide) "SiC") and	USPAT;	2004/03/30 08:34
		451/398.ccls.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	